

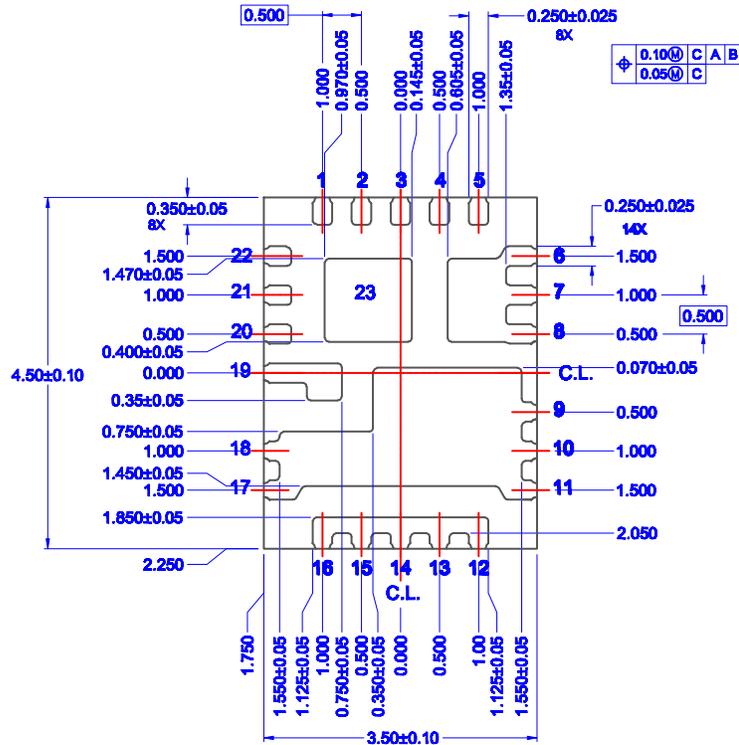
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

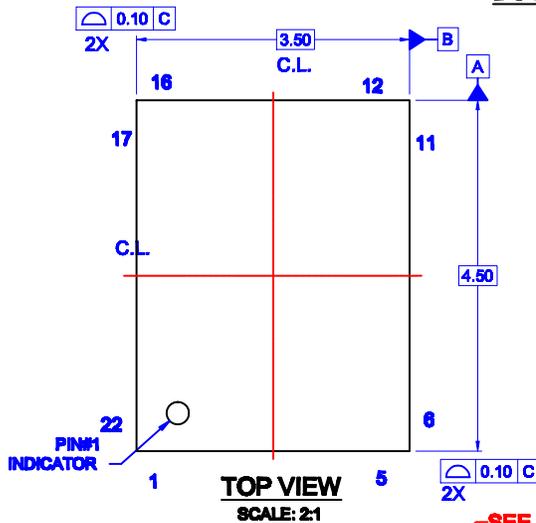


PQFN22 4.5x3.5, 0.5P
CASE 483BU
ISSUE O

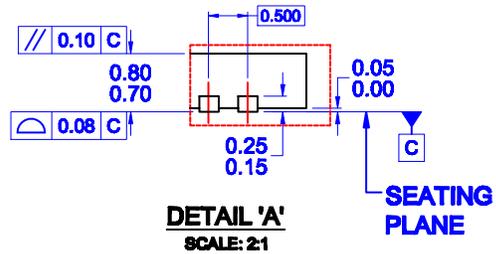
DATE 28 FEB 2017



BOTTOM VIEW
SCALE: 2:1



TOP VIEW
SCALE: 2:1



DETAIL 'A'
SCALE: 2:1



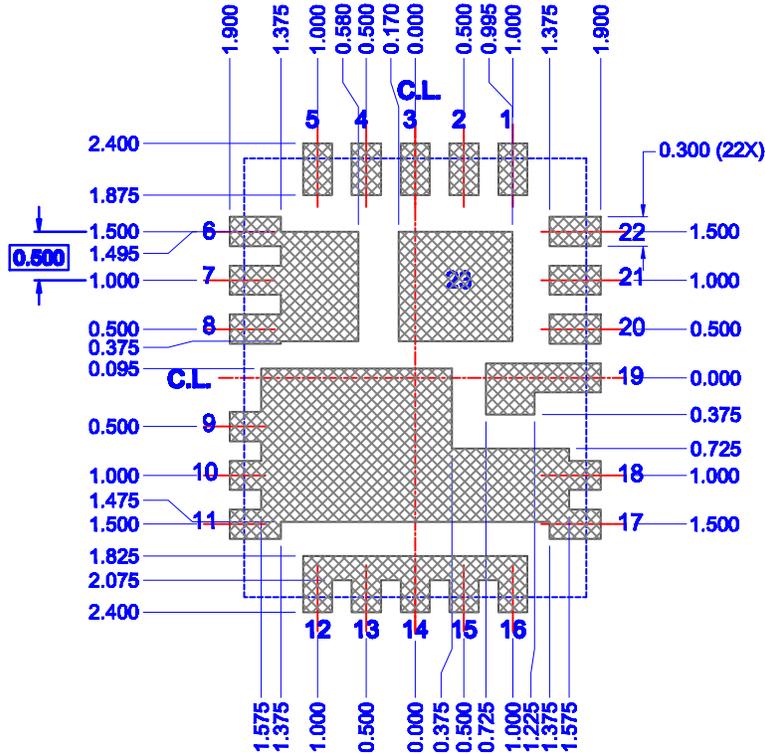
FRONT VIEW
SCALE: 2:1

SEE DETAIL "A"

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PQFN22 4.5x3.5, 0.5P
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ISSUE O

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LAND PATTERN RECOMMENDATION
SCALE 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-220, ISSUE K.01, DATED AUG. 2011.**
- B) ALL DIMENSIONS ARE IN MILLIMETERS.**
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.**
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.**

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